

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC41HGNPBF

(Engineering Calculation)

SSOP

(printed on: 2014-01-20 00:21:13)

TOTAL MASS (g): 0.131851

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004766	1000000	36146.509375	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.040238	975000	305178.65625	
		Iron (Fe)	7439-89-6	0.000990	24000	7508.49511719	
		Phosphorus (P)	7723-14-0	0.000012	300	91.0120697021	
		Zinc (Zn)	7440-66-6	0.000029	700	219.945846558	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-98-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
			<b>Lead Frame Total:</b>		<b>0.041269</b>	<b>1000000</b>	<b>312998.09375</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.002831	1000000	21468.4804688	
			<b>External Plating Total:</b>		<b>0.002831</b>	<b>1000000</b>	<b>21468.4804688</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.000330	1000000	2502.83178711	
			<b>Internal Plating Total:</b>		<b>0.000330</b>	<b>1000000</b>	<b>2502.83178711</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001269	750000	9624.52636719	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000423	250000	3208.17529597	
			<b>Die Attach Total:</b>		<b>0.001692</b>	<b>1000000</b>	<b>12832.7011719</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.006259	103000
Bromine (Br)	40093-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.071761	895000	544259.75	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.000160	2000	1213.4542627	
	<b>Encapsulation Total:</b>				<b>0.080180</b>	<b>1000000</b>	<b>608112.25</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000783	1000000	5938.53808594	

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